L Number	Hits	Search Text	DB	Time stamp
1	323	219/448.11	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 08:58
3	5	(219/448.11 and hot adj plate) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:12
2	38	219/448.11 and hot adj plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:20
4	11	(219/448.11 and hot adj plate) and cool$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:08
5	3912	hot adj plate same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:13
6	35	(hot adj plate same substrate) and temperature with means	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:15
7	1736	(hot adj plate same substrate) and cool$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:15
8	1654	((hot adj plate same substrate) and cool$3) and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:20
9	901	(((hot adj plate same substrate) and cool$3) and temperature) and substrate with thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:20
10	60	((((hot adj plate same substrate) and cool$3) and temperature) and substrate with thickness) and resistive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:38

| 11 | 29 | ((((hot adj plate same substrate) and cool$3) and temperature) and substrate with thickness) and bottom adj plate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/10 09:47 |
| 12 | 7 | ((((hot adj plate same substrate) and cool$3) and temperature) and substrate with thickness) and bottom adj plate with hole | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/10 09:47 |